

In re Patent Application of:

**AMMAR**

Serial No. **09/863,030**

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**In the Specification:**

Please replace the paragraph beginning at page 17, lines 4-17, with the following rewritten paragraph:

This multilayer LTTT alumina substrate is particularly attractive for use with GaAs chip because of its CTE coefficient (7.1). Also, this material has excellent thermal conduction (25-200 W/MK). The MMIC GaAs chips can be attached ~~directly~~ to the substrate using gold tin solder pre-forms or silver epoxy. In cases of thermal concerns, the chips may be attached ~~directly~~ to the base plate using CTE matched shims, or on top of thermal vias that are connected to the bottom surface. These vias can be formed by techniques known to those skilled in the art. For ease of assembly and wire bonding, the top layer (3 to 4 mil thick) will have cut-outs made exactly to the size of the chips (see Figure 5).